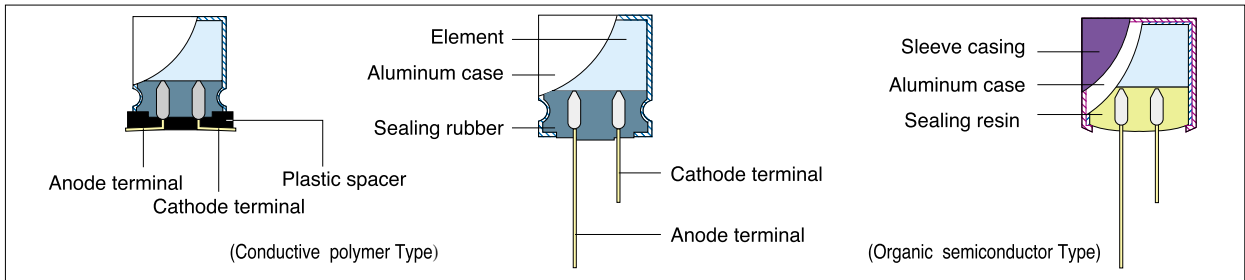
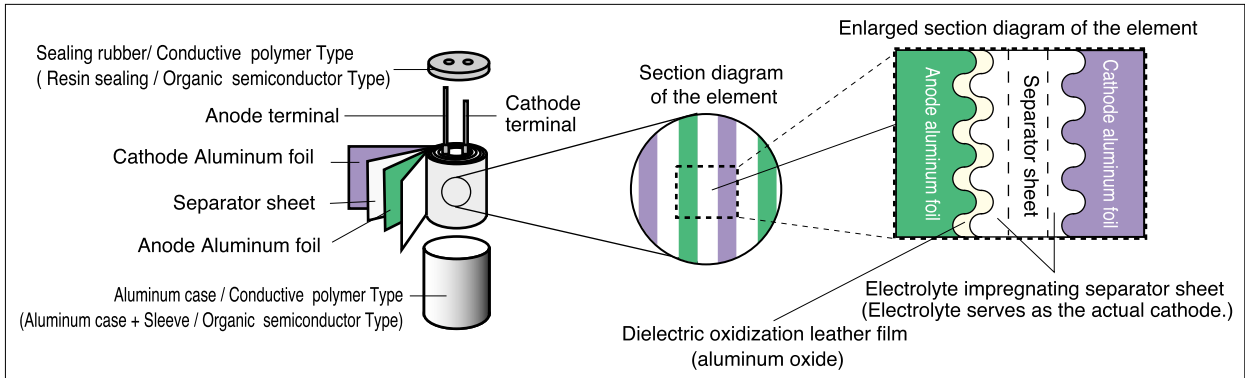


1. Basic structure of OS-CON

OS-CON has a basic construction similar to an aluminum electrolytic capacitor.
A distinctive difference lies in **electrolyte**.

Aluminum electrolytic capacitor	Separator sheet (electrolyte) impregnated with electrolytic solution .	Liquid electrolyte
OS-CON (Organic semiconductor Type)	Separator sheet (electrolyte) impregnated with organic semiconductor .	Solid electrolyte
OS-CON (Conductive polymer Type)	Separator sheet (electrolyte) impregnated with conductive polymer .	Solid electrolyte

1-1. Basic construction

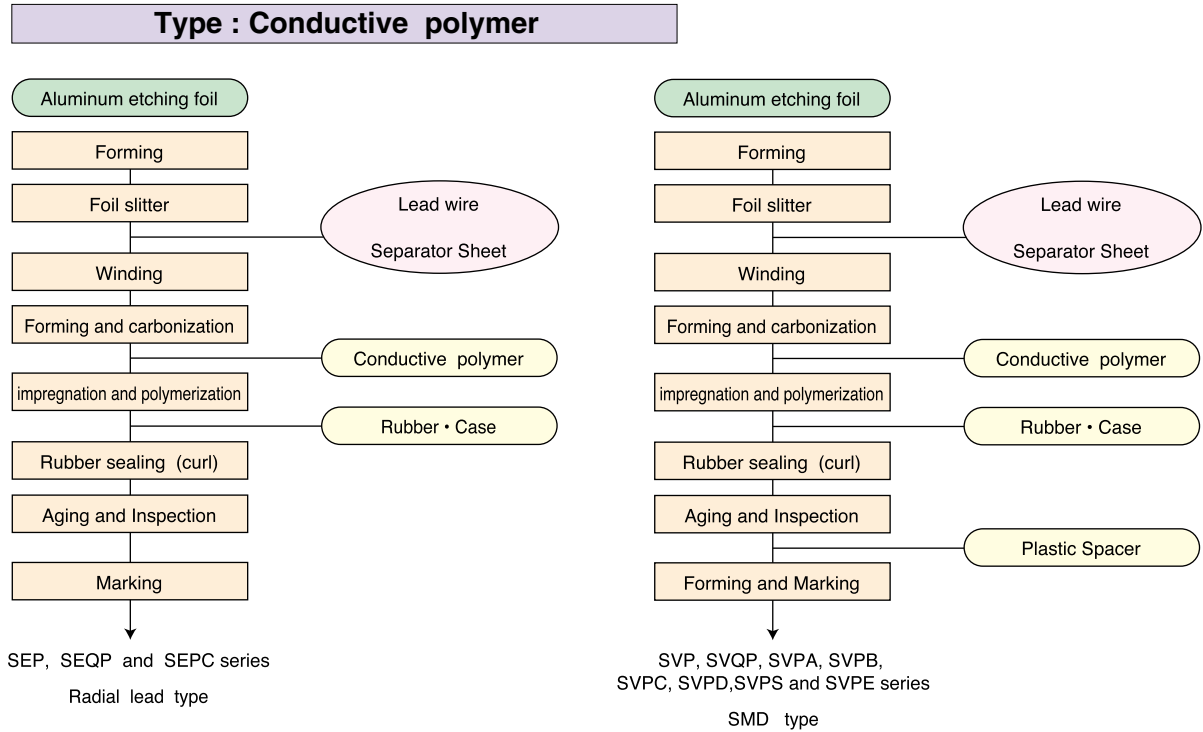


- Increased surface area of the aluminum electrode foil (high-speed processing to form rough surface) results in larger capacitance (greater charge density).
- Electrolyte is impregnated so that the rough dielectric aluminum oxide film at the anode aluminum foil sticks close to the cathode aluminum foil.
- Higher conductivity electrolyte is ideal.

2. Differences of electrolyte and in characteristics between OS-CON and an electrolytic capacitor

	Aluminum electrolytic capacitor	OS-CON	
		Organic semiconductor Type	Conductive polymer Type
Conductivity (See P60,61)	3(mS/cm) • Difficult to lower ESR due to ionic conduction • ESR augments, in particular, in low temperature conditions	300(mS/cm) • High electronic conductivity facilitate to achieve low ESR • ESR is stable in low temperature conditions	3,000(mS/cm) • The highest electronic conductivity, realizing super low ESR. • ESR is stable in low temperature conditions
Reliability, lifespan (See P64,65)	• Liquid electrolyte is evaporable at high temperature • Static capacitance is on the decline at high temperature • Limited lifespan resulting from dry-up • Major fluctuations in temperature characteristics	• Solid electrolyte with little evaporation • Less decrease in static capacitance • Long lifespan even at high temperature • Minor fluctuations in temperature characteristics	• Solid electrolyte with little evaporation • Little decrease in static capacitance • Long lifespan even at high temperature • Very minor fluctuations in temperature characteristics
Temperature coefficient (See P66)	2 times by 10°C reduction 105°C/2,000h → 85°C/8,000h	10 times by 20°C reduction 105°C/2,000h → 85°C/20,000h	10 times by 20°C reduction 105°C/2,000h → 85°C/20,000h

3. OS-CON Manufacturing Method



Type :Organic semiconductor (TCNQ complex salt)

